P & N-Channel 100-V (D-S) MOSFET

These miniature surface mount MOSFETs utilize a high cell density trench process to provide low $r_{DS(on)}$ and to ensure minimal power loss and heat dissipation. Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers, and cordless telephones.

n. Typical applications are DC-DC and power management in portable and wered products such as computers, and cordless telephones.	100	$160 @ V_{GS} = 4.5V$	15
	100	$140 @ V_{GS} = 10V$	16
	-100	290 @ V _{GS} = -4.5V	-11
		$270 @ V_{GS} = -10V$	-12
		<u> </u>	

 $V_{DS}(V)$

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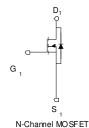
S1 G1 D S2 G2

- $\begin{tabular}{ll} \bullet & Low \ r_{DS(on)} \ provides \ higher \ efficiency \ and \\ extends \ battery \ life \end{tabular}$
- Low thermal impedance copper leadframe DPAK saves board space
- Fast switching speed
- High performance trench technology



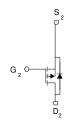


FREE



 $r_{DS(on)} m(\Omega)$

PRODUCT SUMMARY



 $I_{D}(A)$

P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C UNLESS OTHERWISE NOTED)						
Parameter		Symbol	N-Channel	P-Channel	Units	
Drain-Source Voltage		V_{DS}	100	-100	V	
Gate-Source Voltage			±20	±20	V	
	T _A =25°C	I_D	16	-12	A	
Continuous Drain Current ^a	$T_A=25^{\circ}C$ $T_A=70^{\circ}C$		30	-32		
Pulsed Drain Current ^b			40	-40		
Continuous Source Current (Diode Conduction) ^a			30	-30	A	
Power Dissipation ^a	T _A =25°C	P_{D}	50	50	W	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 to 175		°C	

THERMAL RESISTANCE RATINGS					
Parameter Symbol Maximum Un					
Maximum Junction-to-Ambient ^a	$R_{ heta JA}$	50	°C/W		
Maximum Junction-to-Case	$R_{ heta JC}$	3.0	°C/W		

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Notes

- a. Surface Mounted on 1" x 1" FR4 Board.
- b. Pulse width limited by maximum junction temperature

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SPECIFICATIONS (T _A = 25°C UNLESS OTHERWISE NOTED)								
D	Cl1		Limits				T T •4	
Parameter	Symbol	Test Conditions	Ch	Min	Тур	Max	Unit	
Static								
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{GS} = V_{DS}$, $I_D = 250 \text{ uA}$	N	1			V	
Gate-Tilleshold Voltage	▼ GS(th)	$V_{GS} = V_{DS}$, $I_D = -250 \text{ uA}$	P	-1			·	
Gate-Body Leakage	I_{GSS}	$V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$	P	P ±10		±100	n A	
Gate-Body Leakage	¹ GSS	$V_{cs} = 20 \text{ V}, V_{DS} = 0 \text{ V}$	N			±100	nA	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -80 \text{ V}, V_{GS} = 0 \text{ V}$	P			-1	uA	
Zero Gate Voltage Drain Current	¹ DSS	$V_{DS} = 80 \text{ V}, V_{GS} = 0 \text{ V}$	N			1		
On-State Drain Current ^a	ī	$V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$	N	N 20			Λ	
On-State Drain Current	$I_{D(on)}$	$V_{DS} = -5 \text{ V}, V_{GS} = -10 \text{ V}$	P	-20			Α	
		VGS = 10 V, ID = 1 A	N			140		
		$VGS = 4.5 \text{ V}, I_D = 1 \text{ A}$	N			160	0	
Drain-Source On-Resistance ^a	r _{DS(on)}	VGS = -10 V, I _D = -1 A	ъ			270	mΩ	
		$VGS = -4.5 \text{ V}, I_D = -1 \text{ A}$	P			290		
	g	$V_{DS} = 15 \text{ V}, I_{D} = 1 \text{ A}$	N		25		S	
Forward Tranconductance ^a	\mathbf{g}_{fs}	$V_{DS} = -15 \text{ V}, I_{D} = -1 \text{ A}$	P		10		3	
Dynamic	·		•			-		
Total Gate Charge	0		N		10			
Total Gate Charge	Q_{g}	N-Channel	P		9		nC	
Gate-Source Charge	0	$V_{DS}=15V, V_{GS}=10V, I_{D}=1A$	N		4			
Gate-Source Charge	Q_{gs}	P-Channel	P		3			
Gate-Drain Charge	Q_{gd}	V _{DS} =-15V, V _{GS} =-10V, I _D =-1A	N		3			
Gate-Diam Charge	Q_{gd}		P		3			
Turn On Dalay Time	t		N		4			
Turn-On Delay Time	t _{d(on)}		P		5		nS	
Rise Time	f	N-Chaneel	N		3			
	t _r	V_{DD} =15V, V_{GS} =10V, I_{D} =1A , R_{GEN} =6 Ω , P-Channel	P		2			
Turn-Off Delay Time	t.	V _{DD} =-15V, V _{GS} =-10V, I _D =-1A	N		30			
Turn-On Delay Time	$t_{d(off)}$	$R_{GEN}=6\Omega$	P		20			
Fall-Time	t _f		N		6			
I MII IIIIR	<u> </u>		P		14		1	

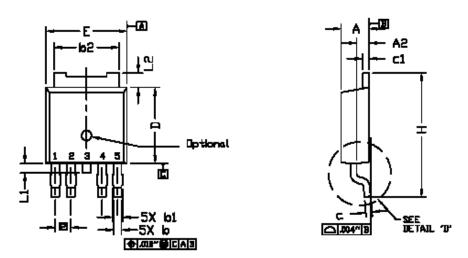
Notes

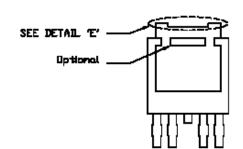
- a. Pulse test: $PW \le 300$ us duty cycle $\le 2\%$.
- b. Guaranteed by design, not subject to production testing.

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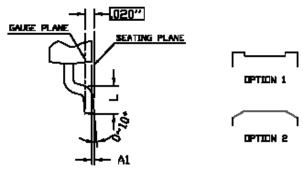
AMD510C

TO252_4L PACKAGE OUTLINE





Analog Power



DETAIL 4	<u> </u>
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DETAIL 'E'

8 Y M	DIMENSION IN MILLIMETERS			DIMENSIONS IN INCHES		
M B O L	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
Α	2.184	2.286	2.388	0.086	0.090	0.094
A1	0.000	_	0.127	0.000	_	0.005
A2	0.889	_	1.143	0.035	_	0.045
b	0.508	_	0.711	0.020	_	0.028
b1	0.584	_	0.787	0.023	_	0.031
b2	4.953	_	5.461	0.195	_	0.215
С	0.457	0.508	0.610	0.018	0.020	0.024
c1	0.457	_	0.610	0.018		0.024
ם	5.969	6.096	6.223	0.235	0.240	0.245
E	6.350	6.604	6.731	0.250	0.260	0.265
8	1.270 BSC.			0.050 BSC.		
Н	9.398	_	10.414	0.370	_	0.410
L	1.270	_	2.032	0.050	_	0.080
L1	_	_	1.016	_	_	0.040
L2	0.889		1.270	0.035		0.050

NOTE

- 1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS. MOLD FLASH SHOULD BE LESS THAN 6 MIL.
 2. DIMENSION L IS MEASURED IN GAUGE PLANE.
 3. TOLERANCE 0.10 mm UNLESS OTHERWISE SPECIFIED.

- 4. CONTROLLING DIMENSION IS MILLIMETER. CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.
- 5, REFER TO JEDEC TO-252 (AD).